**Product data sheet** 

## 1. General description

Silicon Carbide Schottky diode in a TO252 (DPAK) plastic package, designed for high frequency switched-mode power supplies.



## 2. Features and benefits

- · Highly stable switching performance
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- · Reduced losses in associated MOSFET
- Reduced EMI
- · Reduced cooling requirements
- RoHS compliant

# 3. Applications

- · Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

## 4. Quick reference data

### Table 1. Quick reference data

Symbol	Parameter	Conditions		Va	lues		Unit
Absolute	maximum rating						
$V_{RRM}$	repetitive peak reverse voltage			6	50		V
$I_{F(AV)}$	average forward current	$\delta$ = 0.5 ; square-wave pulse; T <sub>mb</sub> ≤ 122 °C; Fig. 1; Fig. 2; Fig. 3		10		А	
T <sub>j</sub>	junction temperature			175		°C	
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static ch	aracteristics						
$V_{F}$	forward voltage	I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.5	1.7	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.8	2.2	V
Dynamic	characteristics		•				
Q <sub>r</sub>	recovered charge	$I_F = 10 \text{ A}$ ; $dI_F/dt = 500 \text{ A/}\mu\text{s}$ ; $V_R = 400 \text{ V}$ ; $T_j = 25 \text{ °C}$ ; Fig. 7		-	14	-	nC

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected		K ——— A
2	K	cathode [1]		K — A 001aaa020
3	А	anode	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	
mb	К	mounting base; connected to cathode		

<sup>[1]</sup> It is not possible to connect to pin 2 of the TO252 package.

## 6. Ordering information

### **Table 3. Ordering information**

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2D10650D	TO252	WNSC2D10650DJ	Reel	2500	TO252NS	14-Nov-2016

# 7. Marking

### Table 4. Marking codes

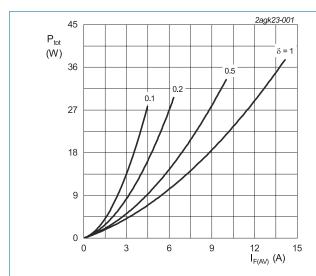
Type number	Marking codes
WNSC2D10650D	WNSC2D 10650D

# 8. Limiting values

### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		650	V
$V_{\text{RWM}}$	crest working reverse voltage		650	V
$V_R$	reverse voltage	DC	650	V
I <sub>F(AV)</sub>	average forward current	$δ$ = 0.5; square-wave pulse; $T_{mb} \le 122$ °C; Fig. 1; Fig. 2; Fig. 3	10	А
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5; $t_p$ = 25 μs; $T_{mb}$ ≤ 122 °C; square-wave pulse	20	А
I <sub>FSM</sub>	non-repetitive peak	$t_p = 10 \text{ ms; } T_{j(init)} = 25 \text{ °C; sine-wave pulse}$	50	А
	forward current	t <sub>p</sub> = 10 μs; T <sub>j(init)</sub> = 25 °C; square-wave pulse	450	А
l <sup>2</sup> t	I <sup>2</sup> t for fusing	sine-wave pulse; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 10 \text{ ms}$	12.5	A <sup>2</sup> s
T <sub>stg</sub>	storage temperature		-55 to 175	°C
T <sub>j</sub>	junction temperature		175	°C



 $I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$  $V_o = 1.024 \text{ V; } R_s = 0.1156 \Omega$ 

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

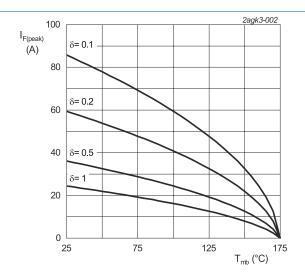
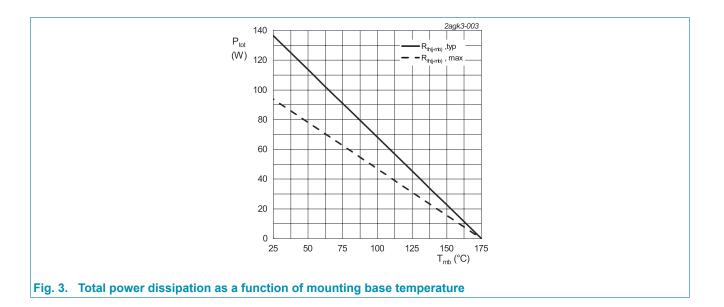


Fig. 2. Current derating as a function of mounting base temperature



## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 4	-	-	1.6	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air	-	50	-	K/W

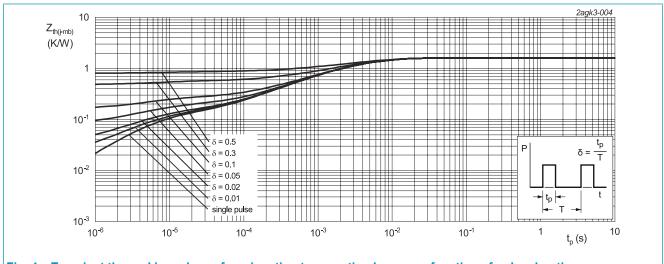
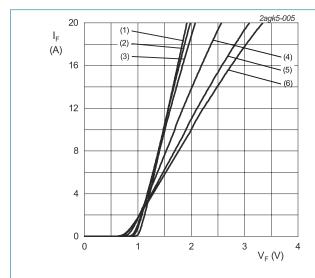


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
$V_{F}$	forward current	I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>	-	1.5	1.7	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>	-	1.8	2.2	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 175 °C; <u>Fig. 5</u>	-	2	2.3	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	0.5	50	μA
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 175 °C; <u>Fig. 6</u>	-	25	250	μA
Dynamic	characteristics					
Q <sub>r</sub>	recovered charge	$I_F = 10 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	14	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C	-	310	-	pF
		f = 1 MHz; V <sub>R</sub> = 300 V; T <sub>j</sub> = 25 °C	-	36	-	pF
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C	-	32	-	pF
E <sub>as</sub>	non-repetitive avalanche energy	I <sub>R</sub> = 5.5 A; L = 5 mH; T <sub>j(init)</sub> = 25 °C	75	-	-	mJ



 $V_o$  = 1.024 V;  $R_s$  = 0.1156  $\Omega$ 

(1)  $T_i = -55$  °C; typical values

(2) T<sub>j</sub> = 0 °C; typical values

(3) T<sub>i</sub> = 25 °C; typical values

(4) T<sub>i</sub> = 100 °C; typical values

(5)  $T_i = 150 \,^{\circ}\text{C}$ ; typical values

(6) T<sub>i</sub> = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

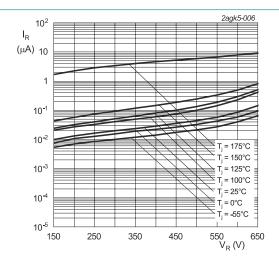
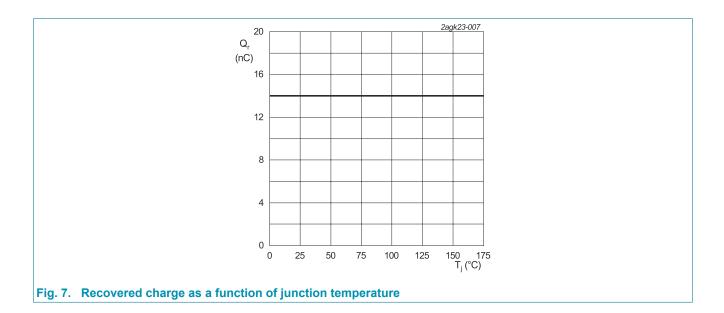
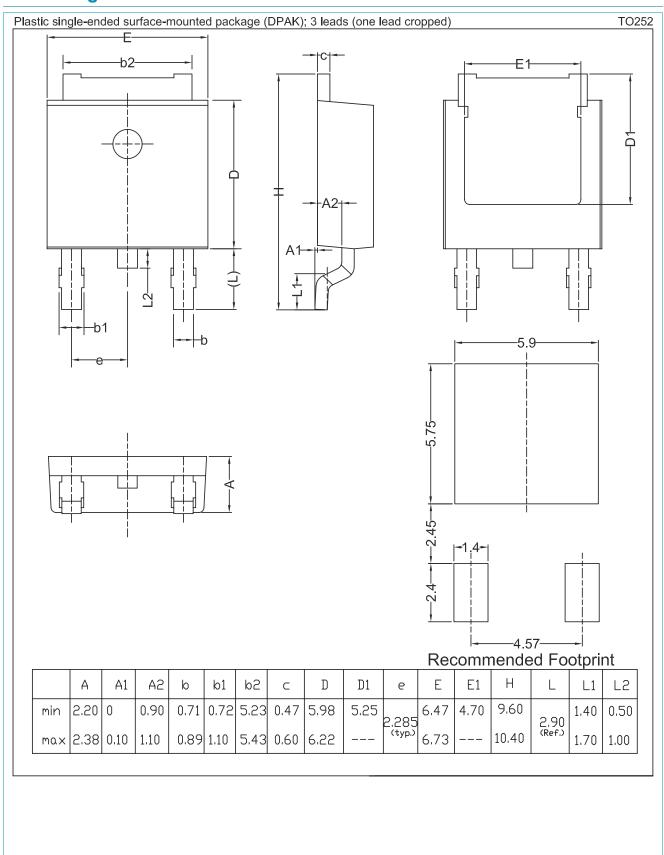


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value



# 11. Package outline



## 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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